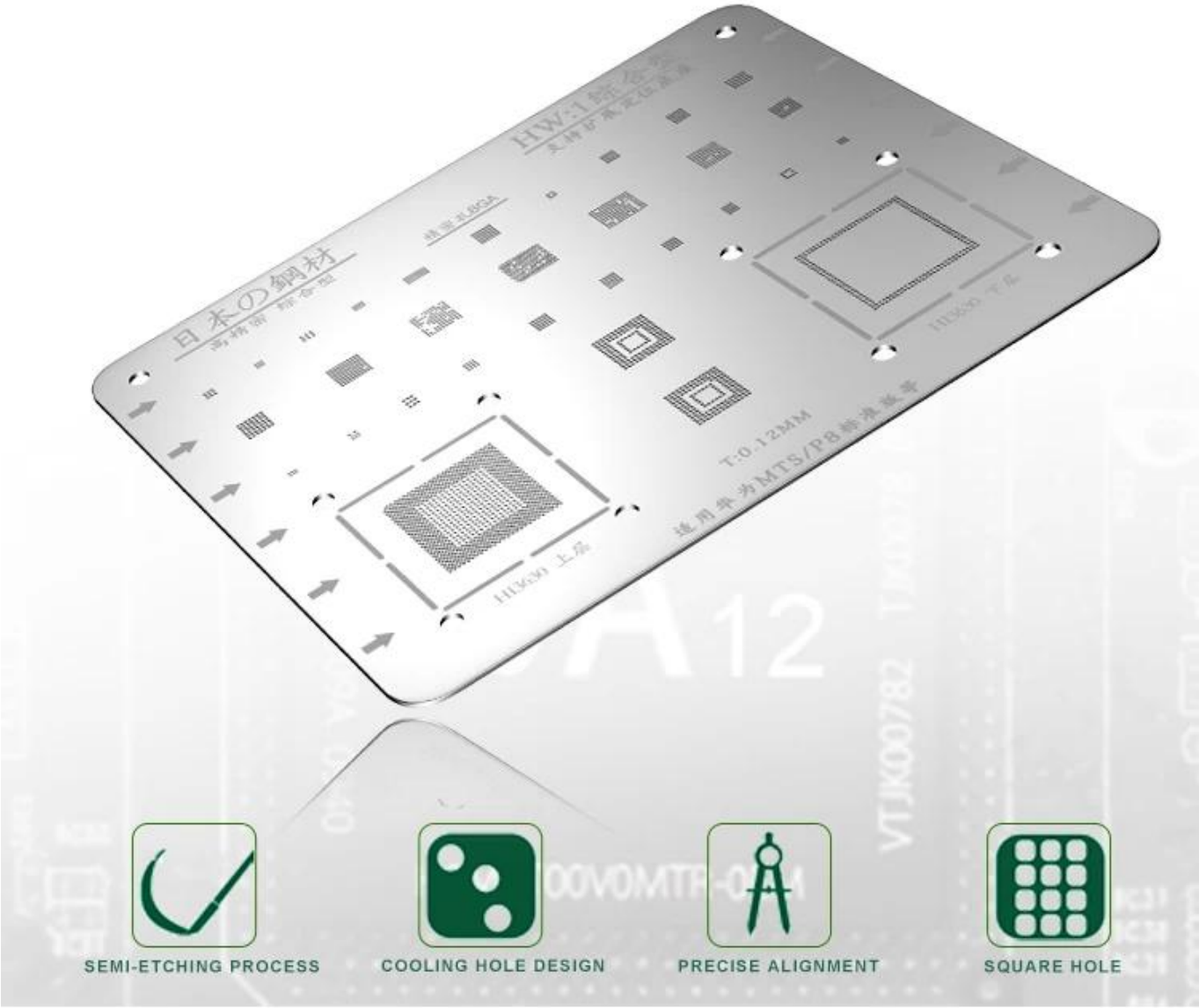
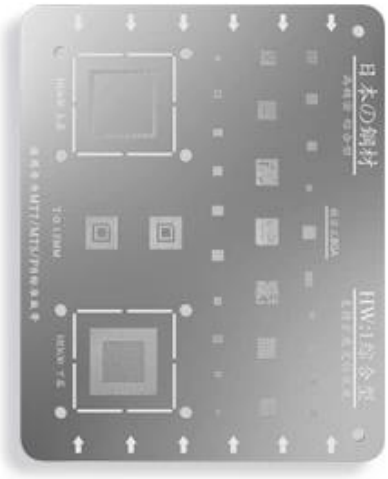
REBALLING STENCIL

— HUAWEI CPU series —



Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g
TYPE	Precise alignment Strong toughness Non-stick ti

▼CHARACTERISTICS

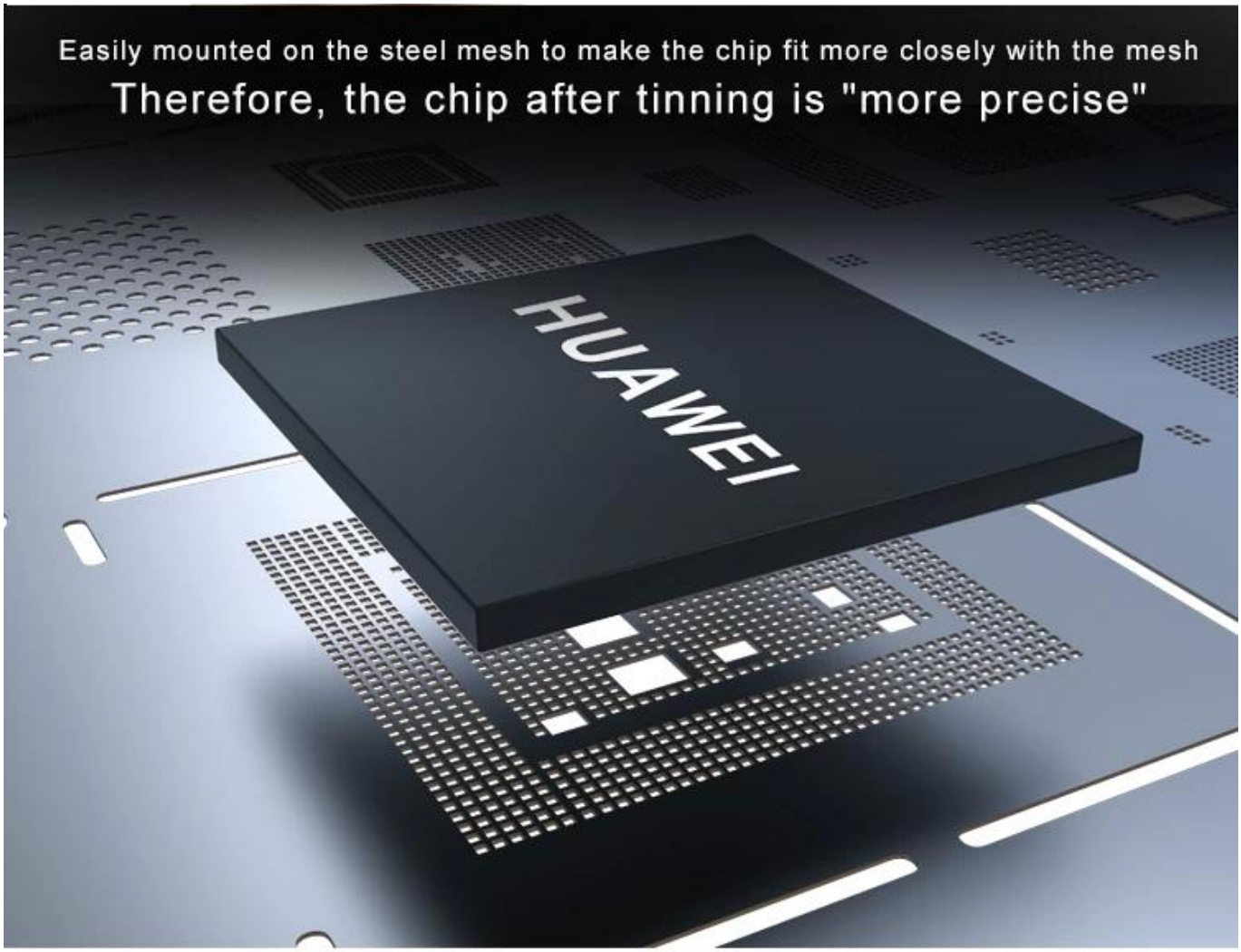
This product is used for BGA tinning repair of the HUAWEI series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

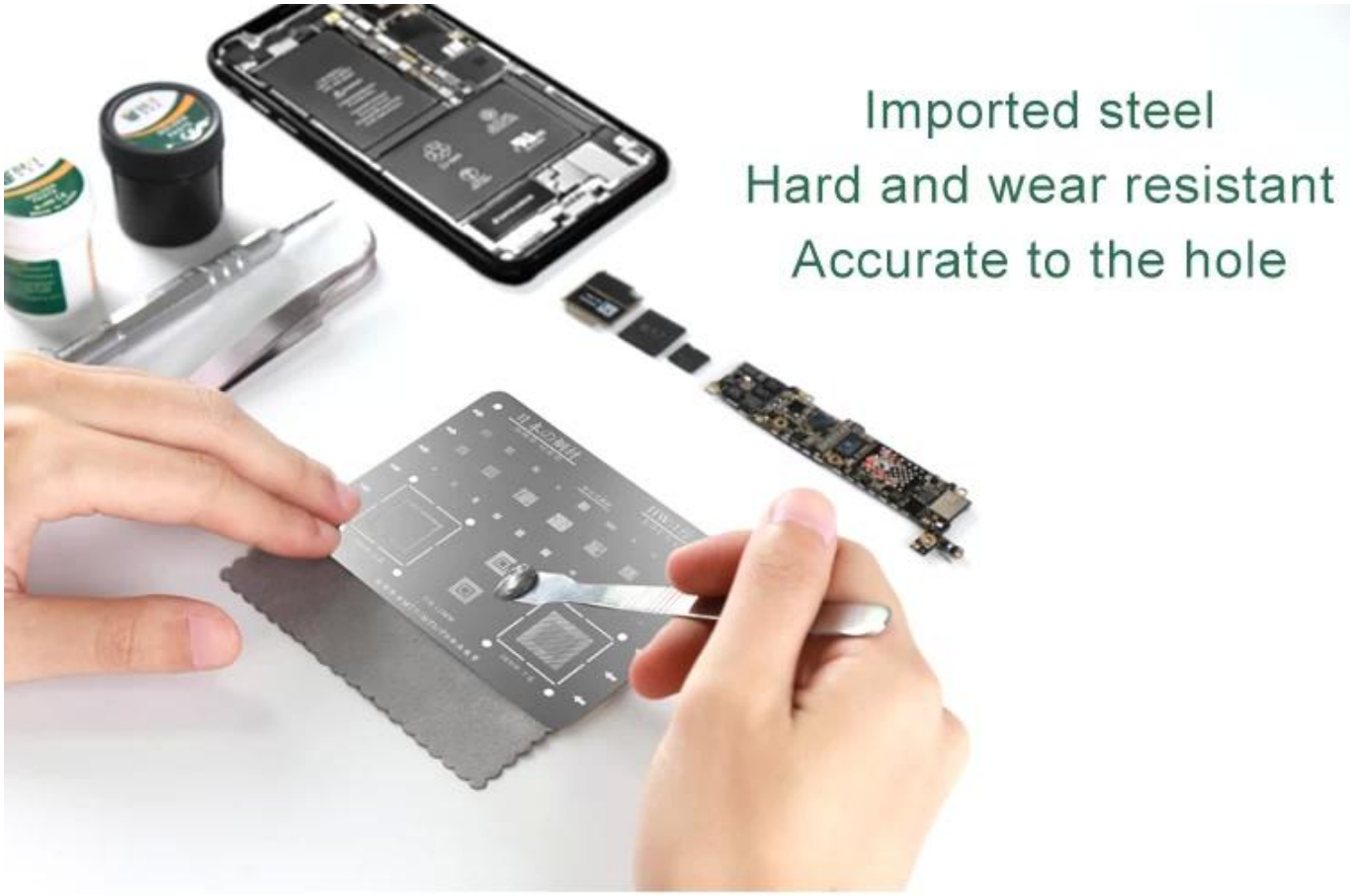
PRODUCT INFORMATION

IMPORTED STEEL

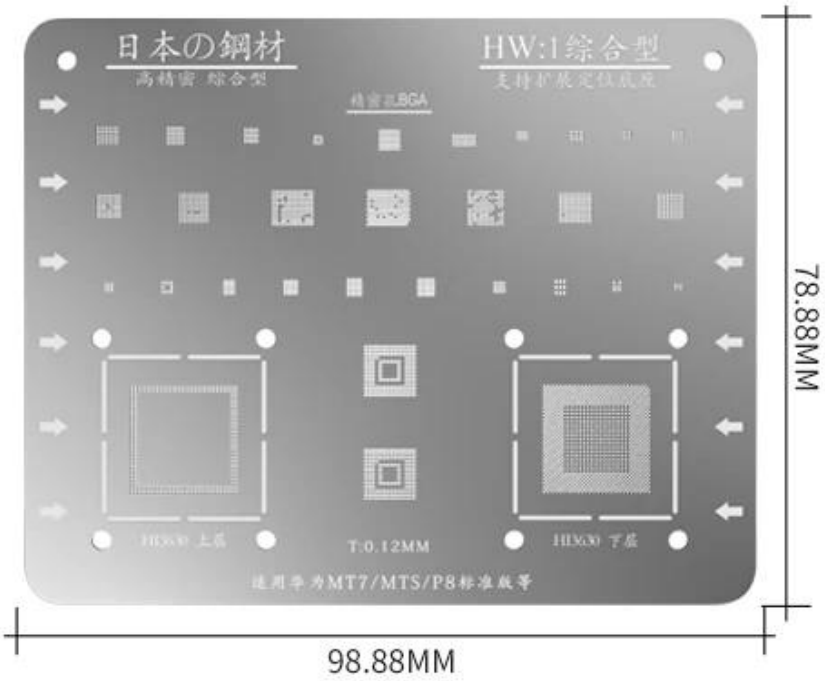
HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY EXCELLENT FORGING PROCESSES, BUT THE REAL CORE LIES IN THE SELECTION OF DELICATE MATERIALS.


Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"
HUAWEI

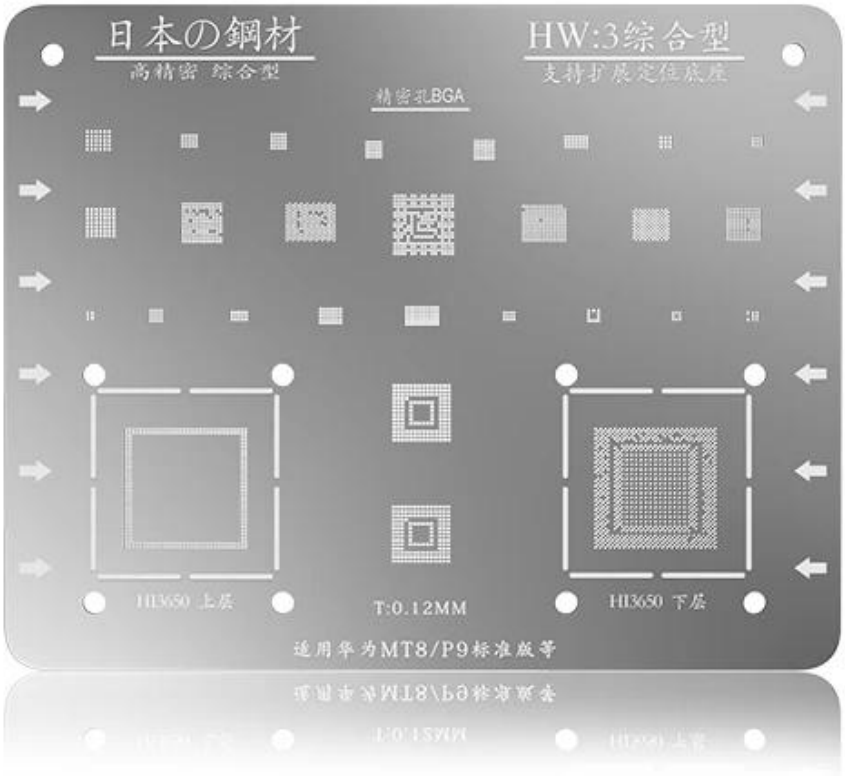

Imported steel
Hard and wear resistant
Accurate to the hole

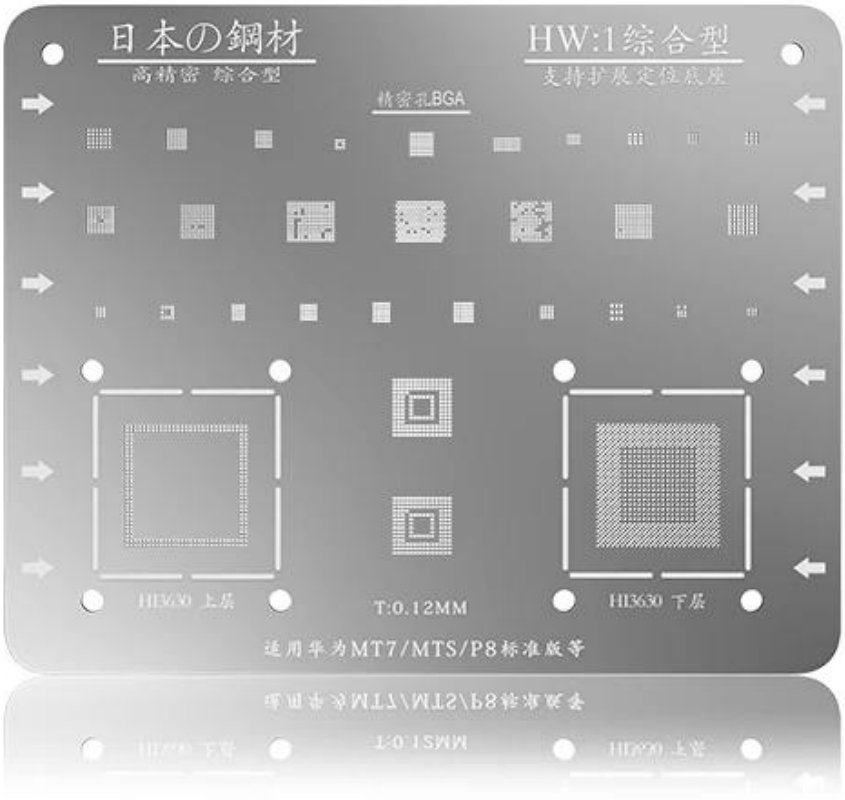
PRODUCT SIZE



Thin to 0.12mm

Precise die-casting Iform heating


日本の鋼材
高精密 综合型
HW:3综合型
支持扩展定位底座
精密孔BGA
HI3650 上层
T:0.12MM
HI3650 下层
适用华为MT8/P9标准版等


日本の鋼材
高精密 综合型
HW:1综合型
支持护展定位底座
精密孔BGA
HI3630 上层
T:0.12MM
HI3630 下层
适用华为MT7/MTS/P8标准版等